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		APPLICANT: Narendar et al.			
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Sheet	1	of	1		

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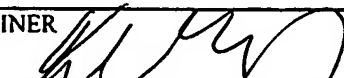
Examiner's Initials	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication or of issue of Cited Document MM-DD-YYYY
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Examiner's Initials	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document (not necessary)	Date of Publication of Cited Document MM-DD-YYYY	Translation (Y/N)
		Office/ Country	Number	Kind Code			
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		R. F. BUCKLEY et al., "Design and Analysis of a Semiconductor Wafer Processing System for 30 mm Wafers," MS Thesis submitted to the Worcester Polytechnic Institute, 12/22/99, pp. i-62.	
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		PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing," McGraw Hill, Fourth Edition, 1990, chapters 3-7.	
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EXAMINER 	DATE CONSIDERED 12/7/05
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*a copy of this reference is not provided because a copy of this reference need not be provided as the reference is a published U.S. Patent or U.S. Patent application and the present application was filed after June 30, 2003.